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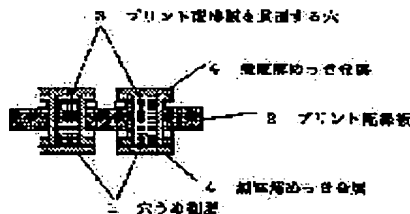
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(54) PRINTED WIRING BOARD

(57)Abstract:

PURPOSE: To allow electrical connection between surface layer circuits through a through hole while ensuring insulation between an inner layer circuit and the surface circuits by filling the through hole in a printed wiring board with a resin containing a plating catalyst and depositing a metal on the surface of the resin by electroless plating.

CONSTITUTION: A composition of an epoxy resin, a cationic photopolymerization starting agent, and a fine silica powder are admixed with a plating catalyst obtained by admixing dimethyl formaldehyde with an epoxy resin and palladium chloride thus producing an ultraviolet ray curing tiller resin 1. The filler resin 1 is filled in through holes 3 of a printed wiring board 2 and cured by irradiating with ultraviolet rays. Copper 4 is then deposited on the surface thereof by electroless plating thus obtaining a both-sided printed wiring board 2. This structure allows positive deposition of copper on the surface of the tiller resin 1 or in a through hole having small diameter made at the filter resin part thus producing a multilayer printed wiring board 2 for increasing the mounting density.



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